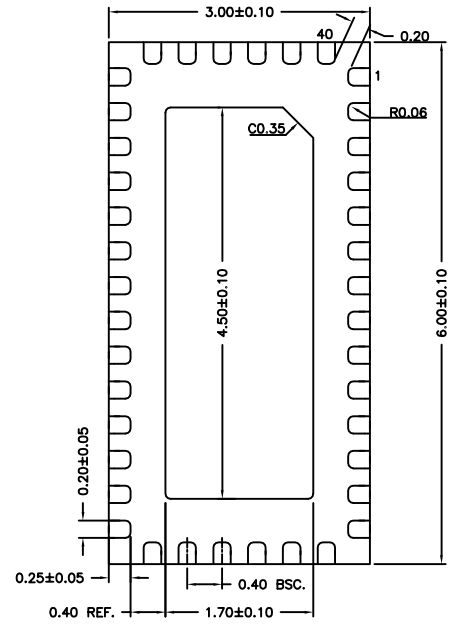
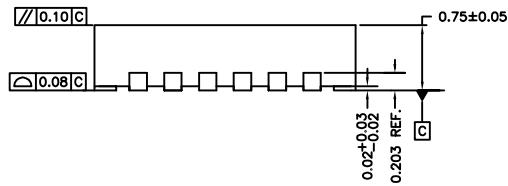
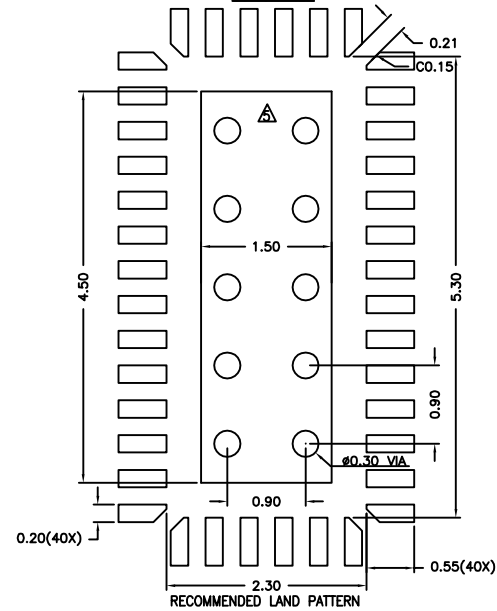


TOP VIEW



BOTTOM VIEW



RECOMMENDED LAND PATTERN

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED)

DIODES
INCORPORATED

PERICOM A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 08/14/18

DESCRIPTION: 40-Pin, TQFN 3X6mm

PACKAGE CODE: ZLD (ZLD40)

DOCUMENT CONTROL #: PD-2239

REVISION: --